



—Low dielectric constant—
Bonding sheet **“A27F”**

Example of use

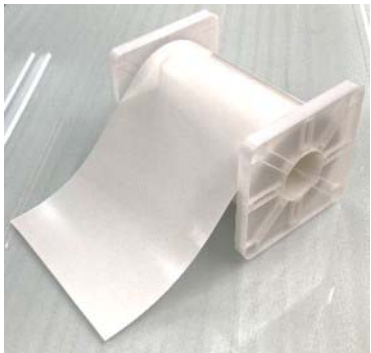
- 5G phone
- Substrate for base station antenna
- ADAS (Advanced Driver-Assistance Systems)



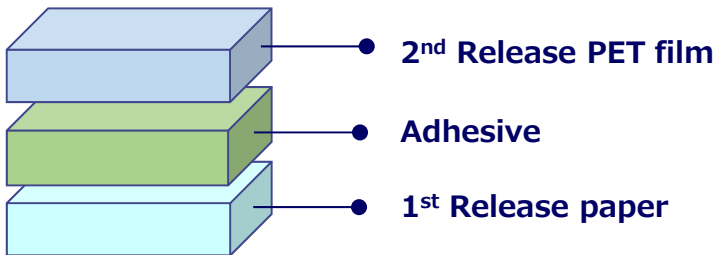
Characteristics

- Low Dk & Low Df.
- Good adhesion to MPI and LCP.
- Good laser workability.

■ Appearance



Product structure

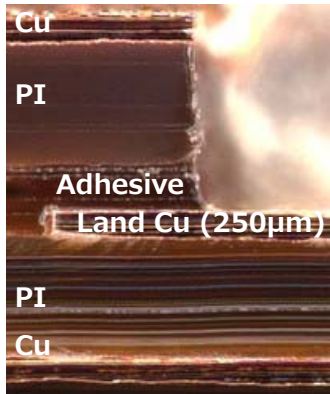


Product Properties

Item		Unit	A27F
Dk (10GHz)		-	2.34
Df (10GHz)		-	0.0013
90° peel strength	MPI	N/cm	14.8
	LCP		11.0
Solder heat resistance (Float in solder bath for 30 sec.)		℃	300

Sample making condition : 180℃×3MPa×60min

<Cross-sectional image after laser processing >



Laser : CO2
Laser wavelength : 10.6μm
Laser intensity : 16W
Processing diameter : 100μm